

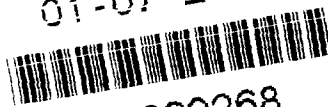
01-07-2003

(Rev. 6-93)

OMB No. 0651-0011 (exp. 4/94)

Patent and Trademark Office

Tab settings →→→



102329268

To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

Name of conveying party(ies):

1) Barbara Vasquez 12-30-02

(Additional name(s) of conveying party(ies) attached) Yes ☒ No

2. Nature of conveyance:

☒ Assignment☐ Merger☐ Security Agreement☐ Change of Name☐ Other**Execution Date:** October 17, 2001

1. Name and address of receiving party(ies):

Name: Infineon Technologies AGInternal Address: PatentabteilungStreet Address: Ridlerstrasse 55City: MuenchenState: GermanyZIP: 80339Additional name(s) & address(es) attached Yes ☐ NoOFFICE OF PUBLIC RECORDS
2002 DEC 20 AM 10:05
FINANCE SECTION

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is:

A. Patent Application No.(s)

09/970,977

B. Patent No.(s)

Additional numbers attached ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Lerner and Greenberg

Internal Address:

Street Address: P.O. Box 2480City: HollywoodState: FLZIP: 33022

6. Total number of applications and patents involved:

1

7. Total fee (37 CFR 3.41)\$ 40.00☒ Enclosed☐ Authorized to be charged to deposit account

8. Deposit account number:

(Attach duplicate copy of this page by deposit account)

01/06/2003 JJALLAH2 00000037 09970977

01 FC:0021

40.00 DP

DO NOT USE THIS SPACE

9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

DENISE LETTAU

Name of Person Signing

Signature

December 24, 2002

Date

Total number of pages including cover sheet, attachments, and document:

2

Docket No.: L&L-10081

ASSIGNMENT

WHEREAS I, BARBARA VASQUEZ, residing respectively at MÜNCHEN, Germany, have invented certain new and useful improvements in a

METHOD FOR FABRICATING A THIN, FREE-STANDING SEMICONDUCTOR DEVICE LAYER AND FOR MAKING A THREE-DimensionALLY INTEGRATED CIRCUIT

for which an application for Letters Patent of the United States of America was executed on the date of execution of this assignment;

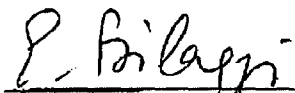
WHEREAS, INFINEON TECHNOLOGIES AG, a German corporation doing business at München, Germany, is desirous of acquiring the entire interest in said invention, and in any and all Letters Patent of the United States that may be obtained therefor;

NOW, THEREFORE, be it known that for and in consideration of our employment by the said corporation and other valuable consideration, the receipt and sufficiency whereof are hereby acknowledged, we have sold, assigned and transferred, and by these presents do sell, assign and transfer unto the said corporation, its legal representatives, successors and assigns, the full and exclusive right to the said invention as fully set forth and described in the above-mentioned application, and to said application and any and all divisions and continuations thereof, and any and all Letters Patent of the United States which may be granted therefor, and any and all reissues of said Letters Patent, the same to be held and enjoyed by the said corporation, its legal representatives, successors and assigns, to the full end of the term for which said Letters Patent may be granted or may be reissued or extended, as fully and entirely as the same would have been held by us had this assignment and sale not been made.

AND I hereby authorize the Commissioner of Patents to issue any and all Letters Patent of the United States on said invention or resulting from said Application and from any and all divisions and continuations thereof to the said corporation as the assignee of the entire right, title and interest in and to the same.

IN TESTIMONY WHEREOF, I have hereunto set our hands and seals.

In the presence of:


E. SCHILAGY

 (LS)
BARBARA VASQUEZ

Date: 17.10.01